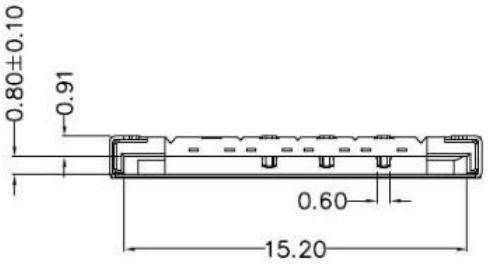
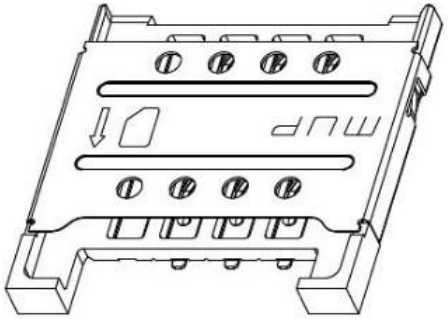
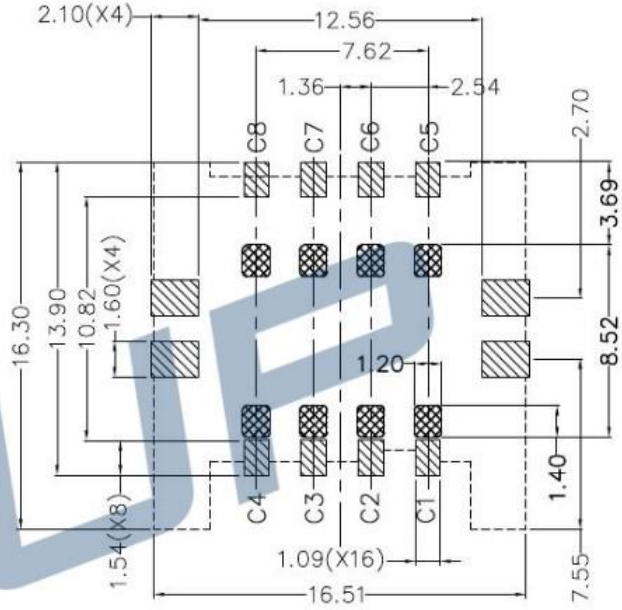
REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					



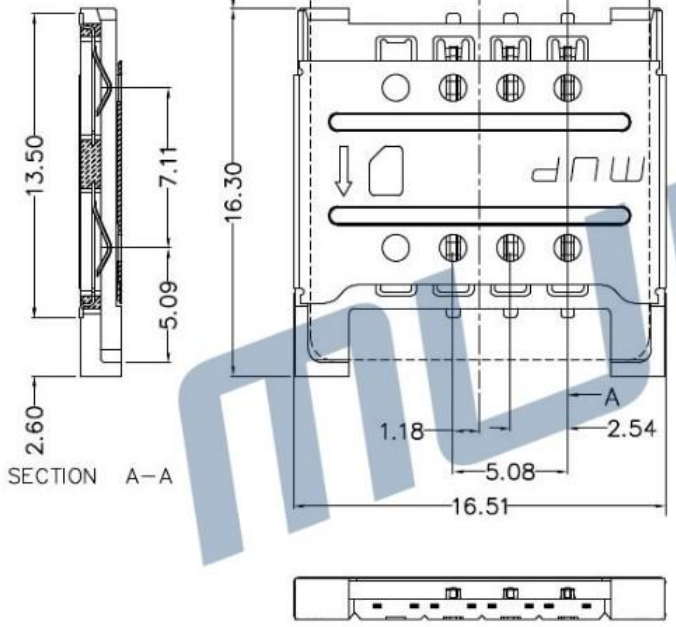


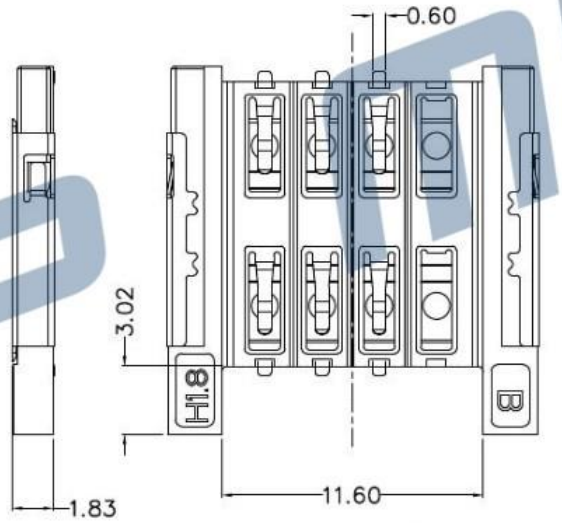


RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

PAD AREA

KEEP AREA





TECHNICAL CHARACTERISTICS

1.General Characteristics
- Dimensions: 16.51LX16.30WX1.80H mm
- Weight: Approx g
- Durability: 5,000 cycles min.

2.Electrical Characteristics
- Contact resistance: 50mΩ typical,100mΩ max
- Insulation resistance: >1000MΩ/500V DC

3.Solderability
- Vaporphase: 215℃,30sec.Max
- IR reflow: 250℃,5sec.Max
- Manual soldering: 370℃,3sec.Max

4.Environmental Characteristics
- Operating temperature: −40℃~+85℃
- Operating humidity: 10%~+95%RH

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi−temp Thermoplastic	Black UL94V−0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless Steel	SMT area:Gold plated

Unless otherwise specified, other tolerance are:

X	±0.35	X°	±5°
X.X	±0.25	X.X°	±4°
X.XX	±0.15	X.XX°	±3°
X.XXX	±0.10	X.XXX°	±2°

PROJ. | UNIT mm | SCALE 1:1

CUSTOMER DRAWING

MUP® MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**

MODEL NO: **MUP C708-5**

TYPE : **H1.80 Without post 6P**

DRAWN	Jimmy 5/10−17'	DWG NO.: DWG−MUP−C708−005
CHECKED	Sean 5/10−17'	
APPROVAL	Simon 5/10−17'	SHEET 1/1 / REVISION X1

MUP MUP